

HAT1055R, HAT1055RJ

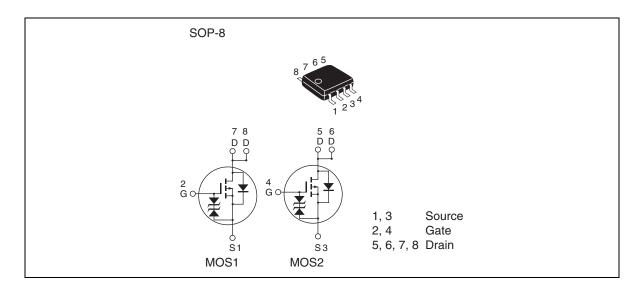
Silicon P Channel Power MOS FET High Speed Power Switching

REJ03G0067-0100Z Rev.1.00 Aug.29.2003

Features

- Low on-resistance
- Capable of 4.5 V gate drive
- High density mounting
- "J" is for Automotive application High temperature D-S leakage guarantee Avalanche rating

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

| Item | Symbol | Ratings | Unit | |
|-------------------------|---|-------------|-------------|----------|
| | | HAT1055R | HAT1055RJ | <u>—</u> |
| Drain to source voltage | V_{DSS} | -60 | -60 | V |
| Gate to source voltage | V _{GSS} | ±20 | ±20 | V |
| Drain current | I _D | - 5 | - 5 | A |
| Drain peak current | I _D (pulse) ^{Note1} | -40 | -40 | A |
| Avalanche current | I _{AP} Note4 | _ | - 5 | A |
| Avalanche energy | E _{AR} Note4 | _ | 2.14 | mJ |
| Channel dissipation | Pch ^{Note2} | 2 | 2 | W |
| Channel dissipation | Pch ^{Note3} | 3 | 3 | W |
| Channel temperature | Tch | 150 | 150 | °C |
| Storage temperature | Tstg | -55 to +150 | -55 to +150 | °C |

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

- 2. 1 Drive operation: When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW \leq 10 s
- 3. 2 Drive operation: When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW \leq 10 s
- 4. Value at Tch = 25°C, Rg \geq 50 Ω

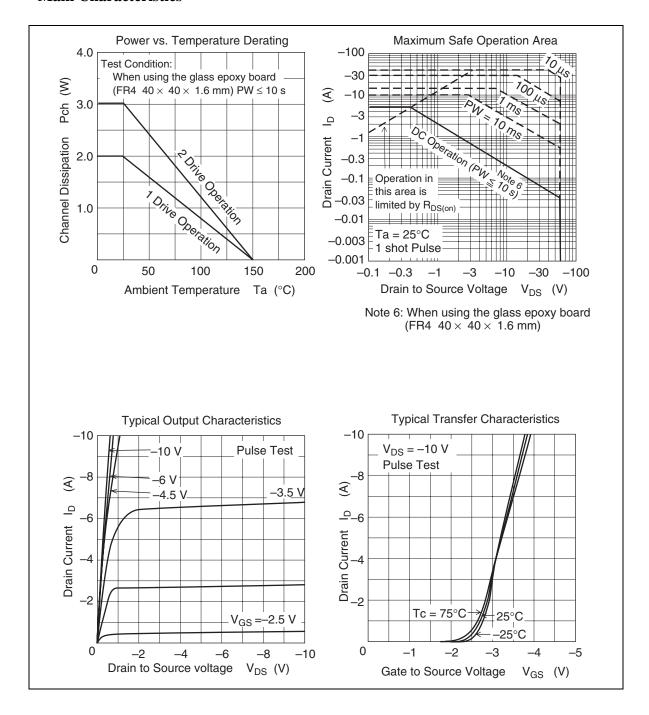
Electrical Characteristics

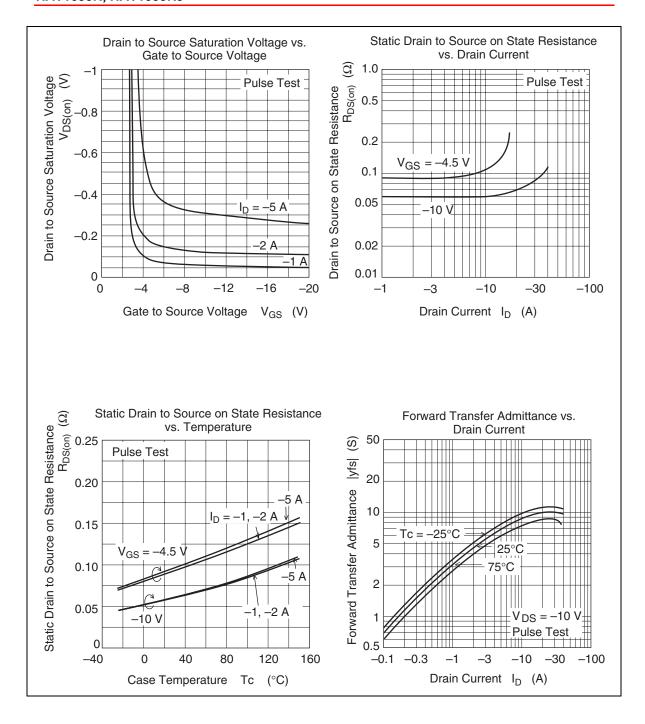
 $(Ta = 25^{\circ}C)$

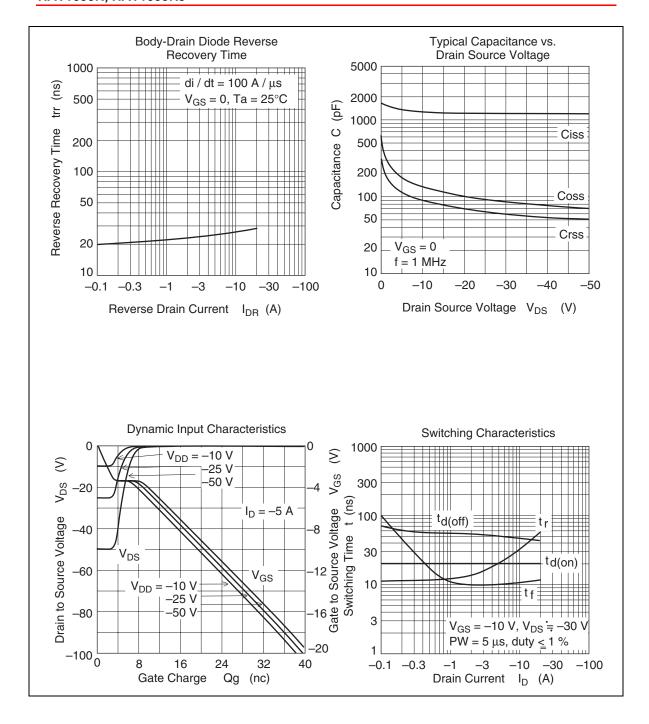
| Item | | Symbol | Min | Тур | Max | Unit | Test Conditions |
|--|-----------|----------------------|------|-------|-------|------|--|
| Drain to source breakdown voltage | | $V_{(BR)DSS}$ | -60 | _ | _ | V | $I_D = -10 \text{ mA}, V_{GS} = 0$ |
| Gate to Source breakdown voltage | | V _{(BR)GSS} | ±20 | _ | _ | V | $I_G = \pm 100 \ \mu A, \ V_{DS} = 0$ |
| Zero gate voltage drain current | | I _{DSS} | _ | _ | -1 | μΑ | $V_{DS} = -60 \text{ V}, V_{GS} = 0$ |
| Zero gate voltage | HAT1055R | I _{DSS} | _ | _ | _ | μΑ | $V_{DS} = -48 \text{ V}, V_{GS} = 0$ |
| drain current | HAT1055RJ | I _{DSS} | _ | _ | -10 | μΑ | Ta = 125°C |
| Gate to source leak current | | I _{GSS} | _ | _ | ±10 | μΑ | $V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$ |
| Gate to source cutoff voltage | | V _{GS(off)} | -1.0 | _ | -2.5 | V | $V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$ |
| Forward transfer admittance | | y _{fs} | 3 | 5 | _ | S | $I_D = -2.5 \text{ A}^{\text{Note5}}, V_{DS} = -10 \text{ V}$ |
| Static drain to source on state | | R _{DS(on)} | _ | 60 | 76 | mΩ | $I_D = -2.5 \text{ A}^{\text{Note5}}, V_{GS} = -10 \text{ V}$ |
| resistance | | R _{DS(on)} | _ | 90 | 130 | mΩ | $I_D = -2.5 \text{ A}^{\text{Note5}}, V_{GS} = -4.5 \text{ V}$ |
| Input capacitance | | Ciss | _ | 1350 | _ | pF | $V_{DS} = -10 \text{ V}, V_{GS} = 0$ |
| Output capacitance | | Coss | _ | 135 | _ | pF | f = 1 MHz |
| Reverse transfer capacitance | | Crss | _ | 85 | _ | pF | _ |
| Total gate charge | | Qg | _ | 21 | _ | nC | V _{DD} = -25 V |
| Gate to source charge | | Qgs | _ | 3 | _ | nC | $V_{GS} = -10 \text{ V}$ |
| Gate to drain charge | | Qgd | _ | 4 | _ | nC | $I_D = -5 A$ |
| Turn-on delay time | | td(on) | _ | 20 | _ | ns | $V_{GS} = -10 \text{ V}, I_{D} = -2.5 \text{ A}$ |
| Rise time | | tr | _ | 15 | _ | ns | V _{DD} ≅ −30 V |
| Turn-off delay time | | td(off) | _ | 55 | _ | ns | $R_L = 12 \Omega$ |
| Fall time | | tf | _ | 10 | _ | ns | $R_G = 4.7 \Omega$ |
| Body-drain diode forward voltage | | V_{DF} | _ | -0.85 | -1.10 | V | $I_F = -5 \text{ A}, V_{GS} = 0^{\text{Note5}}$ |
| Body-drain diode reverse recovery time | | trr | _ | 25 | _ | ns | $I_F = -5 \text{ A}, V_{GS} = 0$ diF/dt = 100 A/µs |

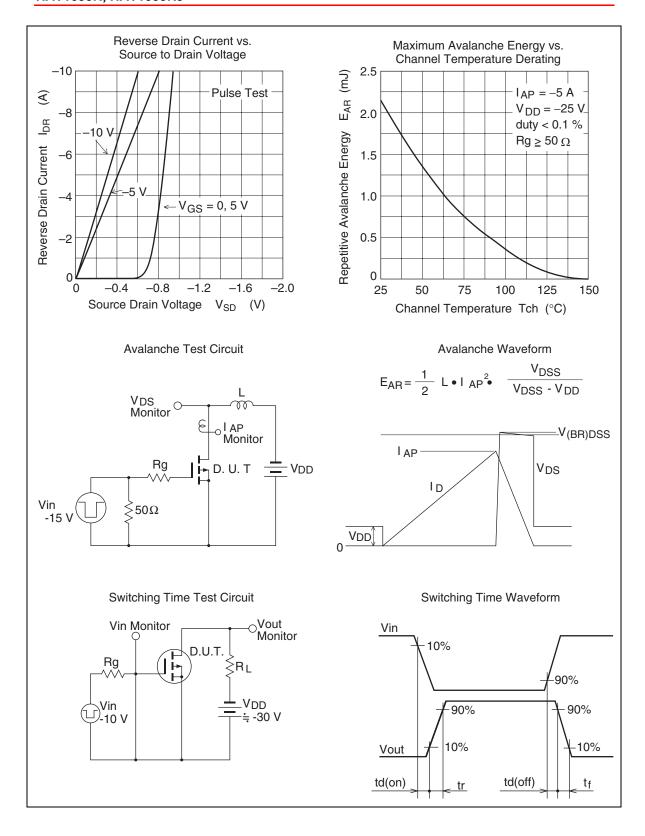
Notes: 5. Pulse test

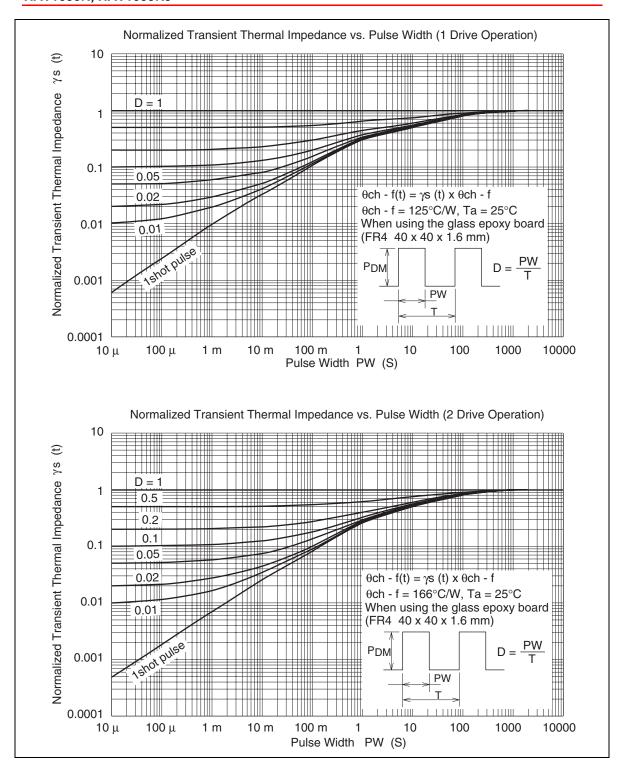
Main Characteristics



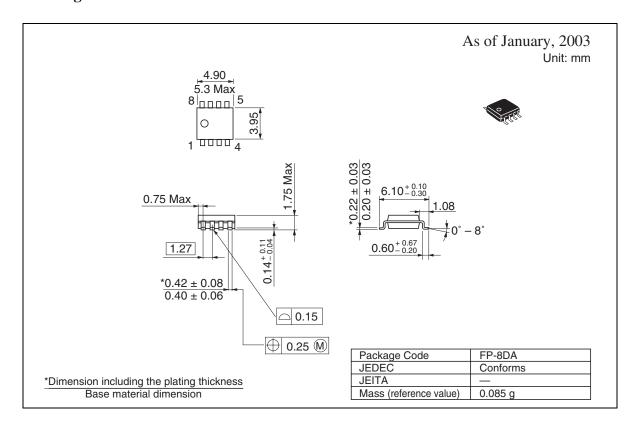








Package Dimensions



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